

WHAT IS CLAIMED IS:

1. A semiconductor device, comprising:
a semiconductor wafer having a plurality of semiconductor chip forming sections, at least one of the semiconductor chip forming sections being electrically connected to at least another segmented semiconductor chip.

2. The semiconductor device according to claim 1, the semiconductor chip forming section that is electrically connected to the another segmented semiconductor chip in the semiconductor wafer being subject to an electrical characteristic examination in advance and determined to be a good product.

3. A semiconductor device, comprising:
a semiconductor wafer equipped with a plurality of semiconductor chip forming sections having electrodes, each of the semiconductor chip forming sections defining a through hole;

a conduction layer that extends via the through hole from at least one surface of the semiconductor chip forming sections on which the electrodes are formed to another surface opposing to the one surface; and

at least another segmented semiconductor chip electrically connected to each of the semiconductor chip forming sections of the semiconductor wafer.

4. The semiconductor device according to claim 3, the other segmented semiconductor chip being electrically connected to the semiconductor chip forming section through the conduction layer.